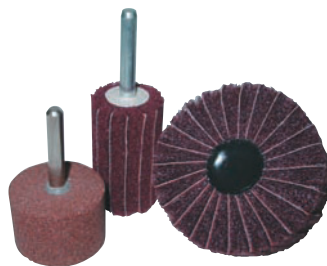


## Industrial Products



• **Permanent Magnet**



• **Abrasive Assembly**



• **Filter Assembly**

| PRODUCT                  | DESCRIPTION  | VISCOSITY<br>HIGH SHEAR<br>RATE (cP) | CURE<br>SCHEDULE       |
|--------------------------|--|--------------------------------------|------------------------|
| <b>Permanent Magnet</b>  |  |                                      |                        |
| 400-76-1                 | Heat curable epoxy adhesive. Outstanding thermal shock resistance and extremely high adhesion. Exceptional thermal stability and resistance to water, humidity and solvents  | 80,000                               | 15 min @ 150°C         |
| 502-09                   | High performance adhesive with exceptional high temperature properties. Induction curable or standard convection cure oven resulting in a very high glass transition temperature   | Paste                                | 30 min @ 160°C         |
| <b>NEW</b> 502-61        | Heat curable flexible epoxy adhesive. Designed to offer the user outstanding flexibility, elongation and peel adhesive strength, while delivering extremely high adhesion. Exceptional thermal stability and resistance to water, humidity and solvents. Superior thermal shock resistance | 65,000                               | 12 min @ 150°C         |
| <b>NEW</b> 504-07        | Heat curable low-sag epoxy adhesive. Forms strong bonds to metals & ceramics. Exceptional thermal stability and resistance to water, humidity and solvents. This product offers high heat resistance and cures in less than 42 seconds via induction or infrared heating                   | 100,000                              | 20 min @ 130°C         |
| <b>NEW</b> 506-12        | Heat curable non-sag epoxy adhesive. Designed for Ni-Cu-Ni plated & Neodymium magnets. Excellent adhesion strength to metals and strong bonds to ceramics. Exceptional thermal stability and resistance to water, humidity and solvents  | Paste                                | 15 min @ 160°C         |
| 702-98                   | Heat curable non-sag epoxy adhesive. Strong bonds to metals and ceramics. Exceptional thermal stability and resistance to water, humidity and solvents   | Paste                                | 15 min @ 150°C         |
| <b>Gel Banding</b>       |  |                                      |                        |
| 505-96                   | A high performance paste adhesive with exceptional high temperature properties. Cures rapidly in a standard convection cure oven resulting in a very high glass transition temperature   | Paste                                | 15 min @ 150°C         |
| 702-80                   | Non-sag epoxy. Thermal stability over a broad temperature spectrum. Resistance to solvents, water, and salt. Unique attributes include low thermal conductivity and electrical properties  | Paste                                | 10 min @ 150°C         |
| 702-80-140K              | Non-sag epoxy. Thermal stability over a broad temperature spectrum. Resistance to solvents, water, and salt. Unique attributes include low thermal conductivity and electrical properties  | 140,000                              | 20 min @ 150°C         |
| <b>Abrasive Assembly</b> |  |                                      |                        |
| 502-04A/B                | 100% solid, two-part epoxy encapsulating compound. Material exhibits medium viscosity and low exotherm while incorporating a convenient volumetric mix ratio of 1:1  | 25,000                               | 25 min @ 25°C<br>(Gel) |
| 505-78                   | Heat curable epoxy adhesive with outstanding mechanical properties and high adhesion. Exceptional thermal stability and resistance to water, humidity and solvents   | 3,000                                | 30 min @ 160°C         |
| 702-98                   | Heat curable non-sag epoxy adhesive. Strong bonds to metals and ceramics. Exceptional thermal stability and resistance to water, humidity and solvents   | Paste                                | 15 min @ 150°C         |
| <b>Filter Assembly</b>   |  |                                      |                        |
| 200-26-2                 | Heat cured epoxy adhesive designed to adhere filter end caps. The material will exhibit outstanding adhesive properties and good chemical resistance   | 50,000                               | 30 min @ 120°C         |
| 503-80                   | Heat curable non-sag epoxy adhesive. Excellent adhesion strength to metals and strong bonds to ceramics. Exceptional thermal stability and resistance to a variety of chemicals  | Paste                                | 15 min @ 150°C         |
| 702-97                   | Self leveling, heat cured epoxy adhesive and sealing compound. Rapid cure at moderate temperatures. Yields high heat and chemical resistant. Resistance to water, solvents, skydrol, and other harsh chemicals   | 25,000                               | 20 min @ 120°C         |
| 703-25                   | Heat cured epoxy that is highly filled to produce excellent heat resistance. Resistance to strong solvents, gasoline, Freon, salt water, mild acids, and continuous high temperatures  | 60,000                               | 30 min @ 150°C         |